# **XP04654** (XP4654)

## Silicon NPN epitaxial planar type (Tr1) Silicon PNP epitaxial planar type (Tr2)

### For high-speed switching

#### ■ Features

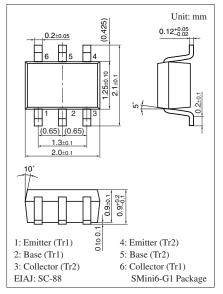
- Two elements incorporated into one package
- Reduction of the mounting area and assembly cost by one half

### ■ Basic Part Number

• 2SC3757 + 2SA1738

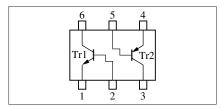
### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Tr1	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	40	V	
	Collector-emitter voltage (E-B short)	V <sub>CES</sub>	40	V	
	Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V	
	Collector current	$I_C$	100	mA	
	Peak collector current	$I_{CP}$	300	mA	
Tr2	Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-15	V	
	Collector-emitter voltage (E-B short)	V <sub>CES</sub>	-15	V	
	Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-4	V	
	Collector current	$I_{C}$	-50	mA	
	Peak collector current	$I_{CP}$	-100	mA	
Overall	Total power dissipation	P <sub>T</sub>	150	mW	
	Junction temperature	$T_{j}$	150	°C	
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



Marking Symbol: ED

### Internal Connection



Note) The part number in the parenthesis shows conventional part number.

## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

### • Tr1

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 40 \text{ V}, I_{E} = 0$			0.1	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 4 \text{ V}, I_{C} = 0$			0.1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 1 \text{ V}, I_{C} = 10 \text{ mA}$	60		320	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$		0.17	0.25	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$			1.0	V
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$		450		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2	6	pF
(Common base, input open circuited)						
Turn-on time	t <sub>on</sub>	Refer to the switching time measurement		17		ns
Turn-off time	t <sub>off</sub>	circuit		17		ns
Storage time	t <sub>stg</sub>			10		ns

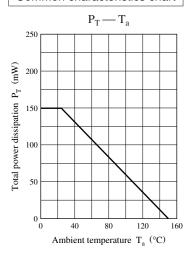
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

### • Tr2

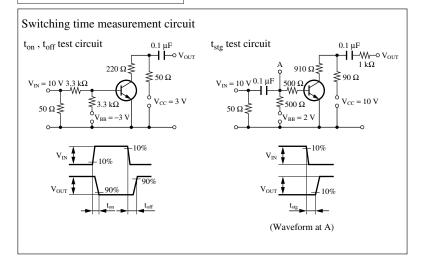
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -8 \text{ V}, I_E = 0$			- 0.1	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -3 \text{ V}, I_C = 0$			- 0.1	μΑ
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = -1 \text{ V}, \ I_{C} = -10 \text{ mA}$	50		150	_
	h <sub>FE2</sub>	$V_{CE} = -1 \ V, \ I_{C} = -1 \ mA$	30			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -1 \text{ mA}$		- 0.1	- 0.2	V
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$	800	1500		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -5 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		1		pF
Turn-on time	t <sub>on</sub>	Refer to the switching time measurement circuit		12		ns
Turn-off time	t <sub>off</sub>			20		ns
Storage time	t <sub>stg</sub>			19		ns

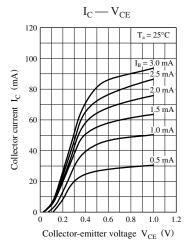
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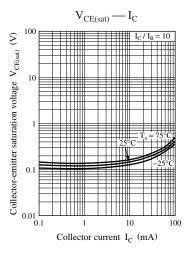
### Common characteristics chart

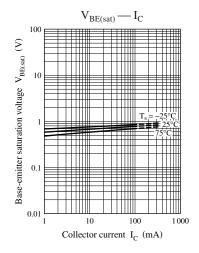


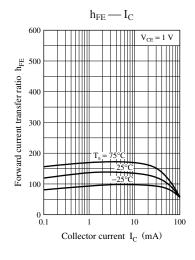
### Characteristics charts of Tr1

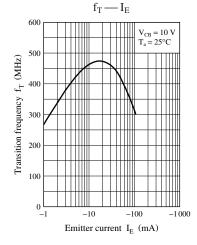


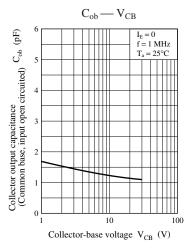




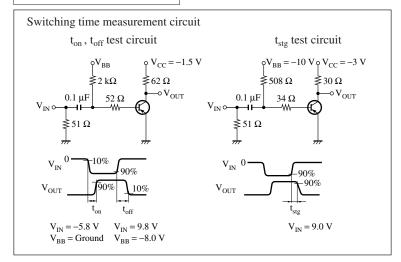


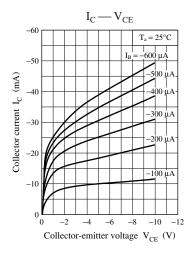


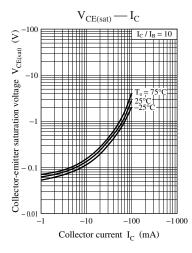


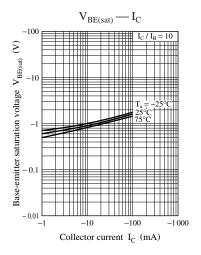


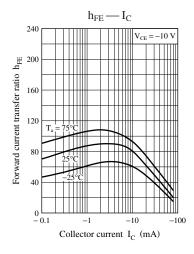
#### Characteristics charts of Tr2

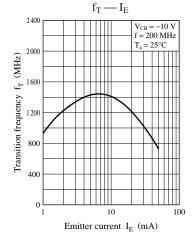


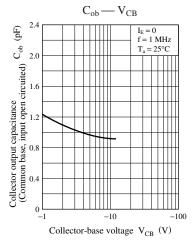












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